



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



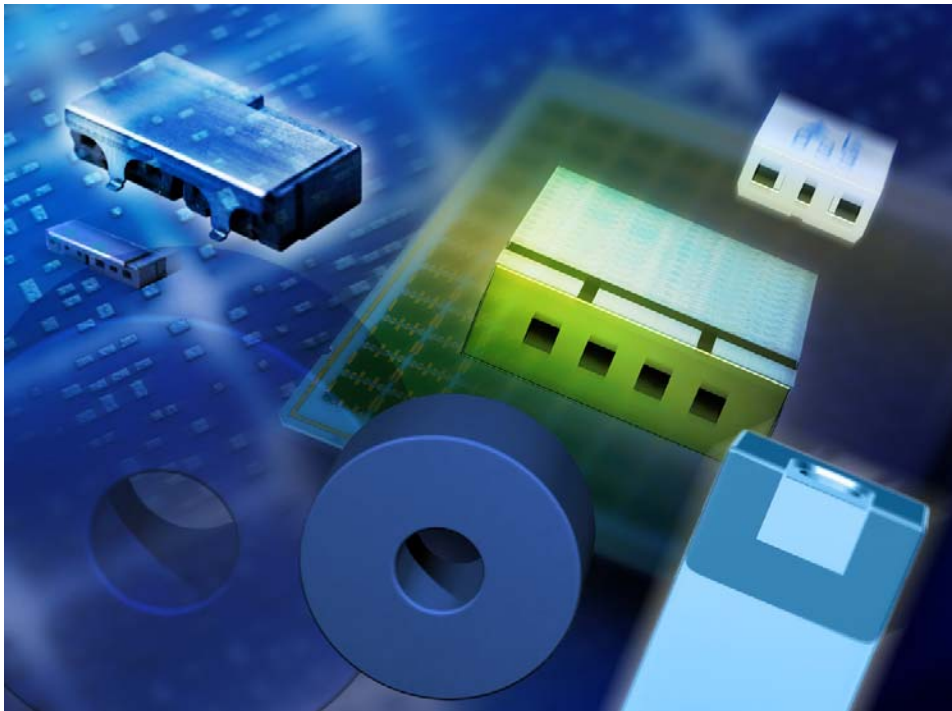
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Design Goal

Features

- SMD filter consisting of coupled resonators with stepped impedances
- $\text{MgTiO}_3 - \text{CaTiO}_3$ ($\epsilon_r = 21 / TC_f = 0 \pm 10 \text{ ppm/K}$) with a coating of copper ($10 \mu\text{m}$) and tin ($>5 \mu\text{m}$)
- Excellent reflow solderability, no migration effect due to copper/tin metallization
- ESD insensitivity and ESD protecting due to filter characteristics

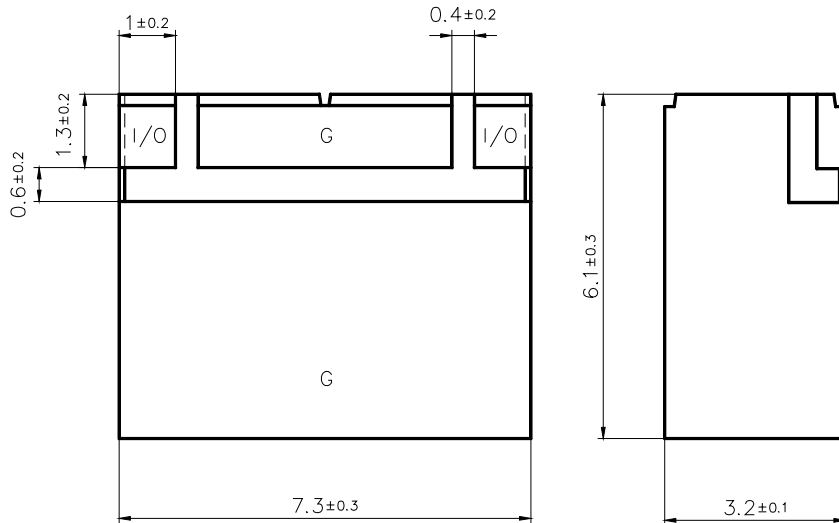
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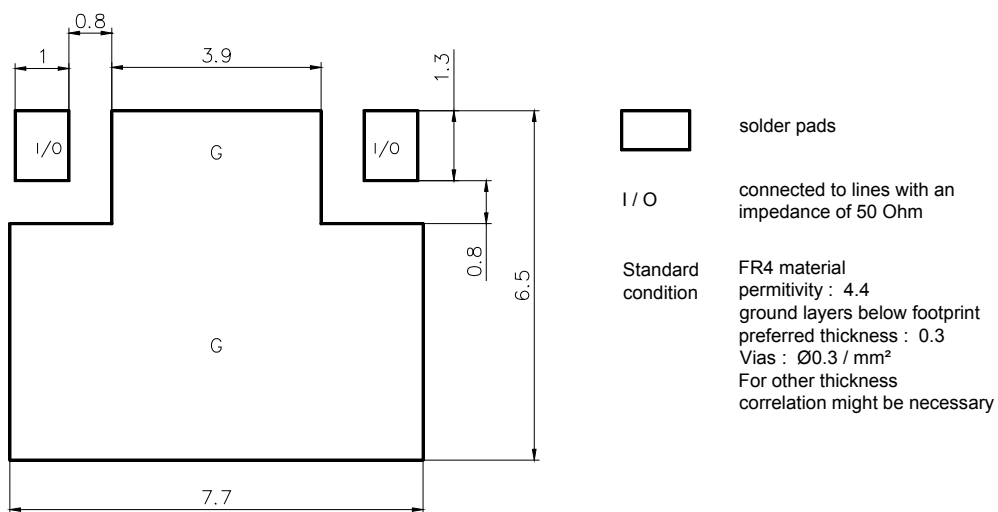
Design Goal

Component drawing



View from below onto the solder terminals and view from beside

Recommended footprint



Design Goal

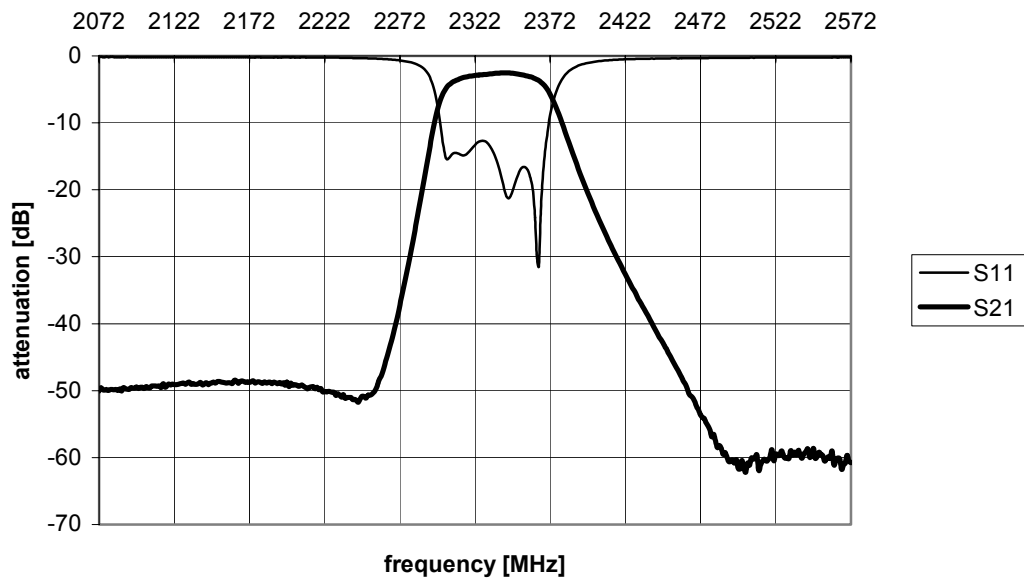
Characteristics

		min.	typ.	max.	
Center frequency	f_c	-	2338.755	-	MHz
Insertion loss	α_{IL}		2.2	2.5	dB
Passband	B	5.5			MHz
Amplitude ripple (peak - peak)	$\Delta\alpha$		0.2	0.5	dB
Standing wave ratio	SWR		1.4	2.0	
Group delay in Passband			15	40	
Impedance	Z		50		Ω
Attenuation	at 2198.755 ($f_c - 140\text{MHz}$)	45	49		dB
	at 2478.755 ($f_c + 140\text{MHz}$)	50	54		dB

Maximum ratings

EC climatic category (IEC 68-1)		- 40/+ 90/56	
Operating temperature	T_{op}	-20 / +80	$^{\circ}\text{C}$

Typical passband characteristic



Design Goal

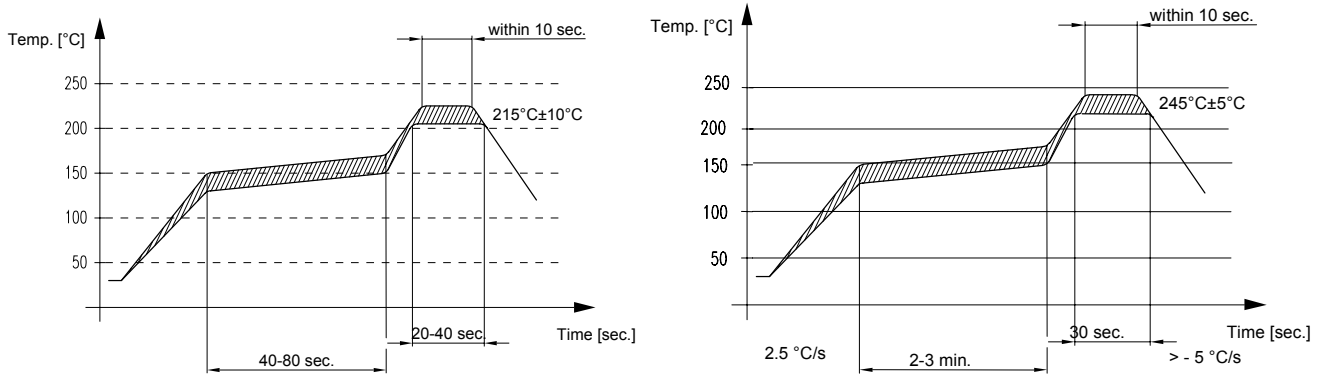
Processing information

- Wettability acc. to IEC 68-2-58: $\geq 75\%$ (after aging)

Soldering Requirements

	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type	reflow	reflow	
Maximum soldering temperature (measuring point on top surface of the component)	235 (max. 2 sec.) 225 (max. 10 sec.)	260 (max. 2 sec.) 250 (max. 10 sec.)	°C °C

Recommended soldering conditions (infrared):



Delivery mode

- Blister tape acc. to IEC 286-3, polyester, grey
- Pieces/tape: **t.b.d.**



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The information contained in this data sheet describes the type of component and shall not be considered as guaranteed characteristics. Purchase orders are subject to the General Conditions for the Supply of Products and Services of the Electrical and Electronics Industry recommended by the ZVEI (German Electrical and Electronic Manufacturers' Association), unless otherwise agreed.

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